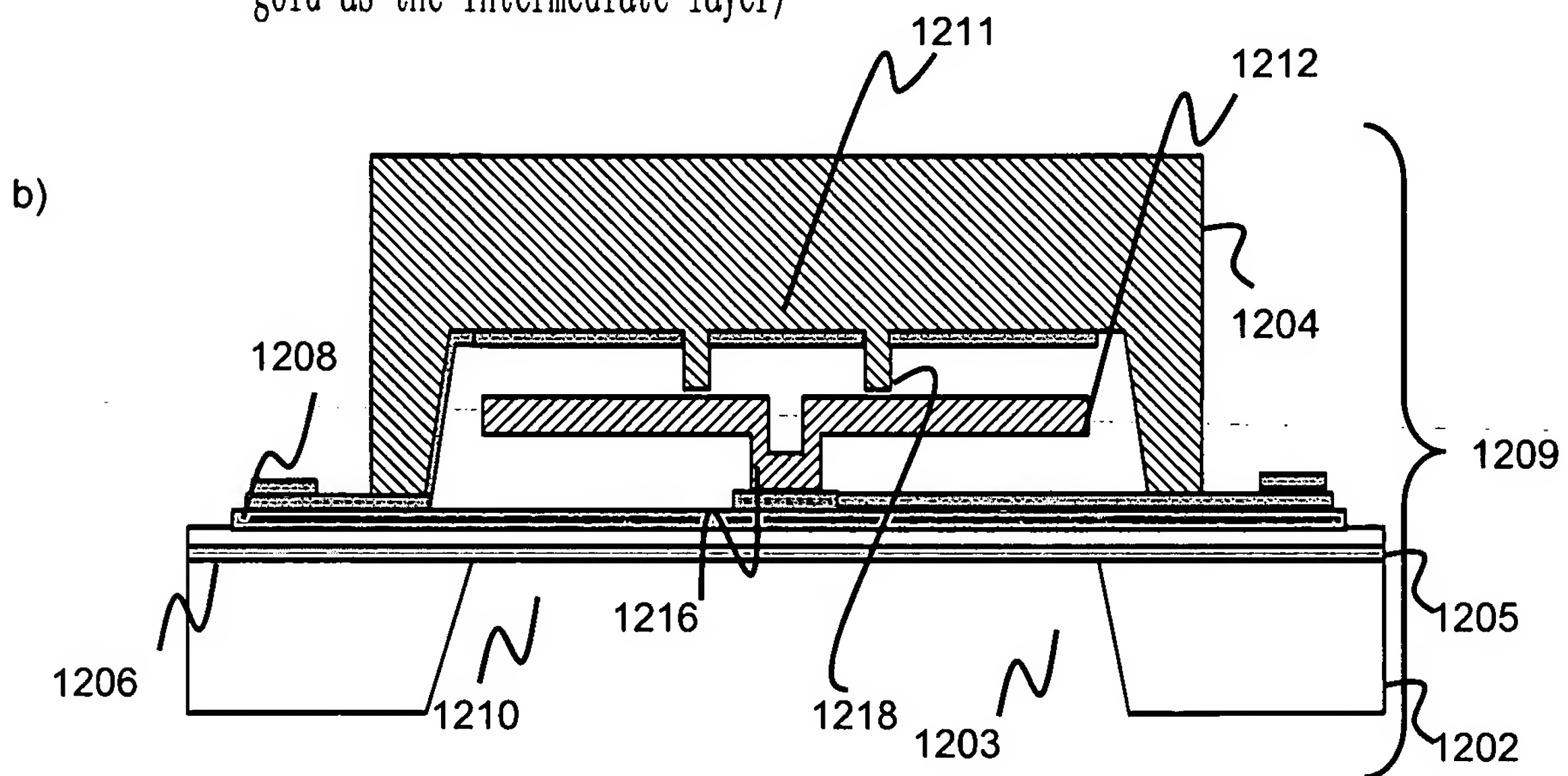


(A). Silicon to glass intermediate bonding (using gold as the intermediate layer)



(B). Backside wet etch using BHF (Etching stops at Silicon dioxide layer)

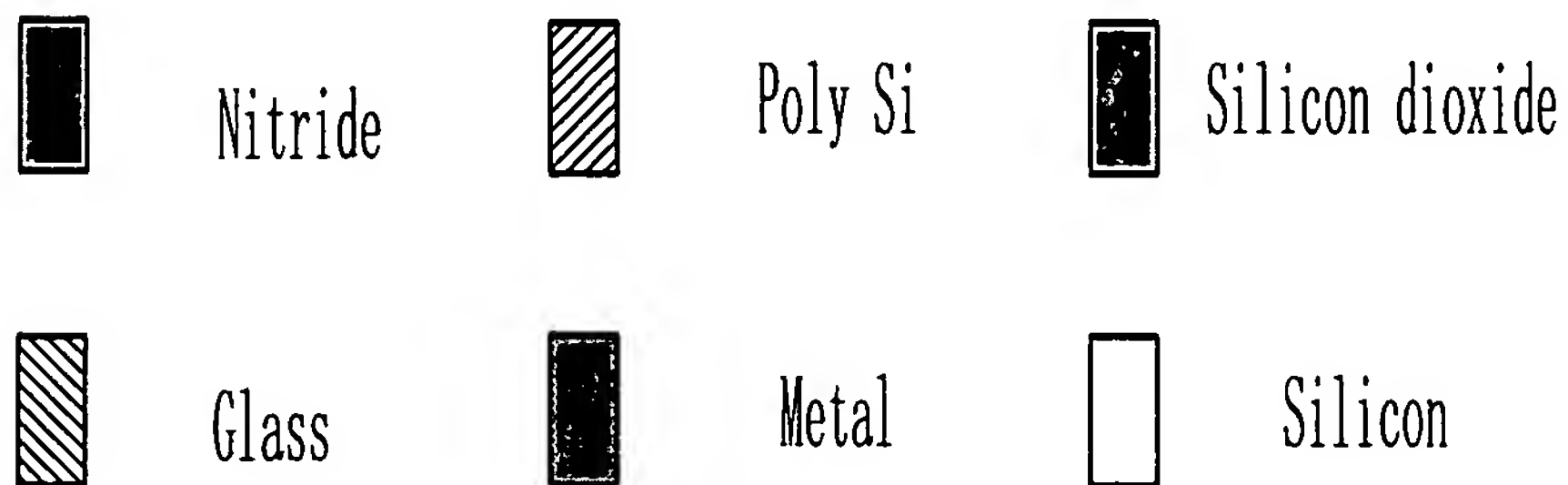


Figure 12